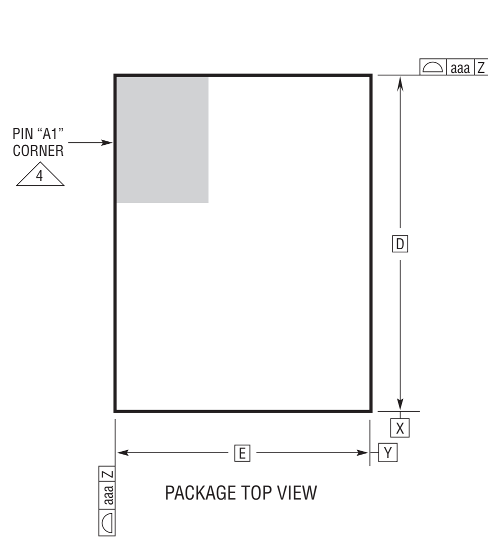
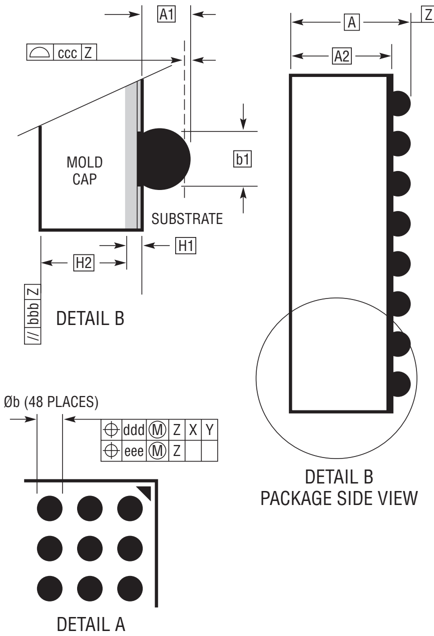
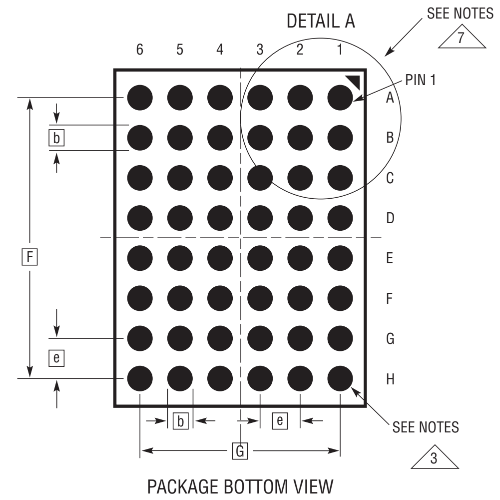
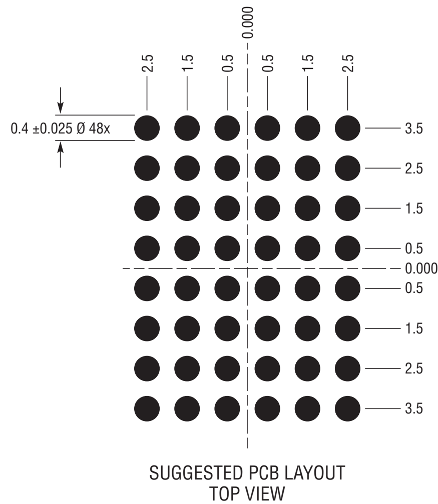
BGA Package
48-Lead (9mm × 6.25mm × 3.22mm)
(Reference LTC DWG # 05-08-1977 Rev Ø)



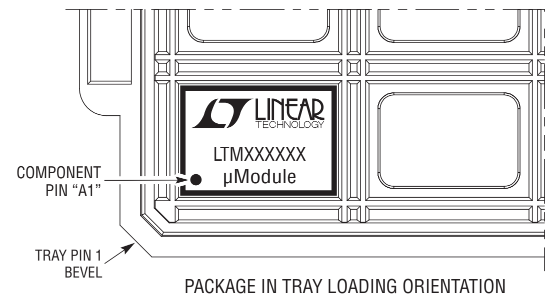






DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.02	3.22	3.42	
A1	0.30	0.40	0.50	
A2	2.72	2.82	2.92	
b	0.45	0.50	0.55	
b1	0.35	0.40	0.45	
D		9.00		
E		6.25		
e		1.00		
F		7.00		
G		5.00		
H1	0.27	0.32	0.37	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 48				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 48 0314 REV Ø